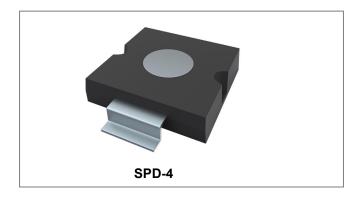






# 123SPD100A Power Surface Mount Schottky Rectifier



#### **Features**

- 175 °C T<sub>J</sub> operation
- Low forward voltage drop
- High surge capacities
- High frequency operation
- Guaranteed reverse avalanche capability
- Low profile surface mount package
- This is a Pb Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

### **Schematic & Pin Configuration**



### **Applications**

- · Switching power supply
- Redundant power subsystems
- Reverse battery protection
- Converters
- Many other high current AC/DC power supplies

### **Maximum Ratings:**

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	-	100	V
Average Rectified Forward Current	I <sub>F (AV)</sub>	50% duty cycle @Tc=116°C, rectangular wave form	120	А
Peak One Cycle Non-Repetitive Surge Current	I <sub>FSM</sub>	8.3 ms, half Sine pulse	1650	Α
Non-Repetitive Avalanche Energy	E <sub>AS</sub>	T <sub>J</sub> =25℃,I <sub>AS</sub> =0.75A, L=40 mH	11.25	mJ
Repetitive Avalanche Current	I <sub>AR</sub>	$I_{AS}$ decaying linearly to 0 in 1 µsec Frequency limited by $T_J$ max. $V_A$ =1.5 $\times$ $V_R$	0.75	Α

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### **Electrical Characteristics:**

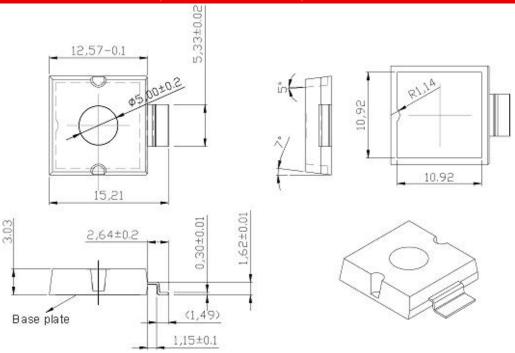
Characteristics	Symbol	Condition	Тур.	Max.	Units
Forward Voltage Drop *	V <sub>F1</sub>	@ 120A, Pulse, T <sub>J</sub> = 25 °C	0.80	0.87	V
	V <sub>F2</sub>	@ 120A, Pulse, T <sub>J</sub> = 125 °C	0.65	0.72	V
Reverse Current*	I <sub>R1</sub>	$@V_R = rated V_R, Pulse, T_J = 25 °C$	0.001	2.0	mA
	I <sub>R2</sub>	$@V_R = rated V_R$ , Pulse, $T_J = 125  ^{\circ}C$	0.8	48.0	mA
Junction Capacitance	Ст	$@V_R = 5V, T_C = 25 °C f_{SIG} = 1MHz$	2400	3000	pF
Voltage Rate of Change	dv/dt	-	-	10,000	V/μs

<sup>\*</sup> Pulse width < 300 µs, duty cycle < 2%

## **Thermal-Mechanical Specifications:**

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	TJ	-	-55 to +175	°C
Storage Temperature	T <sub>stg</sub>	-	-55 to +175	°C
Typical Thermal Resistance Junction to Case	R <sub>θJC</sub>	DC operation	0.20	°C/W
Approximate Weight	wt	-	2.35	g

### **Mechanical Dimensions SPD-4(Inches/Millimeters)**



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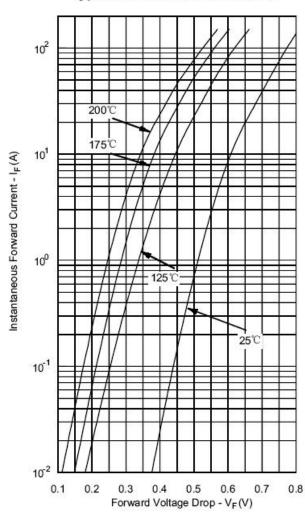




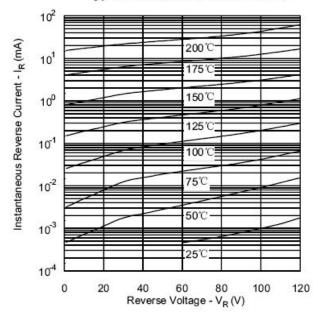


#### **Ratings and Characteristics Curves**

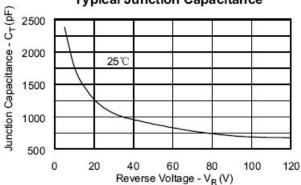
**Typical Forward Characteristics** 



#### Typical Reverse Characteristics



#### Typical Junction Capacitance

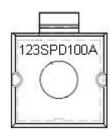


### **Tube Specification**

Device	Package	Shipping	
123SPD100A	SPD-4(Pb-Free)	64pcs/ bag	

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

### **Marking Diagram**



123SPD100A =Part Name

Cautions: Molding resin

Epoxy resin UL:94V-0

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